Material Declaration Data Sheet

Intel®PRO/1000 GT Quad Port Server Adapter
D30274, PWLA8494GT, PWLA8494GTBLK, PWLA8494GTG1P20
**= any combination of alpha-numeric characters*
Pb Free Product: ***SLI***

Product Weight (grams): *128 grams*
Manufacturer: Intel Corporation
Issue Date: *2/7/2007*

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

* Quantity limit of 0.1% by mass (1000 PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
* Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration *Select the appropriate RoHS Declaration(s) from below.*

☐ The part does not contain RoHS restricted substances per the definition above.

☐ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

☐ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in optical and filter glass.

☐ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.

☑ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in high melting temperature type solders (i.e. tin-lead sloder alloys containing more than 85% lead).

☑ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in electronic ceramic parts

☑ The part does contain RoHS substances per the definition above and uses the following exemption: Lead in glass of electronic components.

☐ This part contains RoHS restricted materials (lead) above the threshold level. Exemption status cannot be determined since this part may be used in exempt and/or non-exempt applications.

☐ Other:

Where the part is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

LEVEL A MATERIALS AND SUBSTANCES

Materials from Annex A of the EIA/EICTA/JGPSSI Material Composition Declaration Guide and listed in the table below are not contained in this product in quantities above the threshold level for these materials as stated in the EIA/EICTA/JGPSSI Material Composition Declaration Guide, nor intentionally added to this product.

Asbestos	Mercury/Mercury Compounds	Polychlorinated Naphthalenes
Azo colorants	Ozone Depleting Substances	Radioactive Substances
Cadmium /Cadmium Compounds	Polybrominated Biphenyls (PBBs)	Shortchain Chlorinated Paraffins
Hexavalent Chromium	Polybrominated Diphenylethers (PBDEs)	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Hexavalent Chromium Compounds	Polychlorinated Biphenyls (PCBs)	Tributyl Tin Oxide (TBTO)

This product contains lead/lead compounds.

	Description of Use	*Location in Product*	Material Concentration (ppm)
Lead/Lead Compounds	***glass in electronic components, ceramic, first level interconnects***	***resistors, capacitors, magnetics***	***1020***

LEVEL B MATERIALS AND SUBSTANCES

Antimony/Antimony Compounds	Bismuth/Bismuth Compounds
Arsenic/Arsenic Compounds	Brominated Flame Retardants
Beryllium/Beryllium Compounds	Nickel/Nickel Compounds

If this product contains materials listed in Annex B of the EIA/EICTA/JGPSSI Material Composition Declaration Guide above the threshold level of 1000 ppm, those materials/substances are listed below.

Material / Substance	*Description of Use*	*Location in Product*	Material Concentration (ppm)
Brominated Flame Retardant	***Flame Retardant, TBBPA***	***component packaging, Printed wiring boards***	***31400***
Nickel	***Plating***	***Bracket***	***11900***

COMMENTS

1. The data on Level A and B materials and substances are based on analytical testing of the following product: ***PWLA8494GT***
   Individual unit test results may vary due to differences in production and /or sensitivities of analytical testing methods. Data shown on this MDDS reflect part-level testing intended to validate Intel's RoHS compliance systems. Intel's certification of RoHS compliance at the homogenous material level is based on Supplier Declarations of Conformance.
2. This data sheet is based on the product specified and other products within the family are similar.
3. Data in parts per million (ppm) can be used to estimate content for other products within this family.
4. Material mass can be estimated by multiplying concentration (ppm) by product weight.
5. The remainder of this package consists of non-reportable metals (e.g., tin, iron, etc.), epoxy resin and other non-metal materials.

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关于符合中国《电子信息产品污染控制管理办法》的声明
Management Methods on Control of Pollution From Electronic Information Products (China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷板组件	×	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。
×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。

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